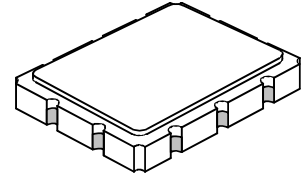


- *Designed for GSM BTS Receiver IF Applications*
- *Compatible with National Semiconductor Chip Set*
- *Very Flexible Impedance Matching*
- *Unbalanced or Balanced Input or Output*
- *9.1 x 7.1 mm Version of the SF1115A-1*
- *Complies with Directive 2002/95/EC (RoHS)*
- *Tape and Reel Standard per ANSI/EIA-481*



SF1115A

199 MHz SAW Filter



SM9171-10

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+15	dBm
Max. DC voltage between any 2 terminals	30	VDC
Storage Temperature Range	-40 to +85	°C
Suitable for lead-free soldering - Max. Soldering Profile	260°C for 30 s	

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units	
Nominal Center Frequency	f_c			199.000		MHz	
Passband	Insertion Loss at f_c 1 db Passband	IL			7.0	dB	
		BW_1		± 100		kHz	
						0.5	dB _{P-P}
		Group Delay Variation over $f_c \pm 100$ kHz	GDV			500	ns _{P-P}
Rejection	Room Temperature f_c+800 to f_c+400 kHz Room Temperature f_c-800 to f_c-400 kHz f_c-800 to f_c-600 and f_c+600 to f_c+800 kHz f_c-30 MHz to f_c-800 kHz f_c+800 kHz to f_c+17 MHz f_c-80 MHz to f_c-30 MHz f_c+17 Mhz to f_c+80 MHz		10			dB	
			10				
			20				
			30				
			30				
			35				
Operating Temperature Range	T_A		-35		+85	°C	
Frequency Temperature Coefficient	FTC			0.032		ppm/°C ²	

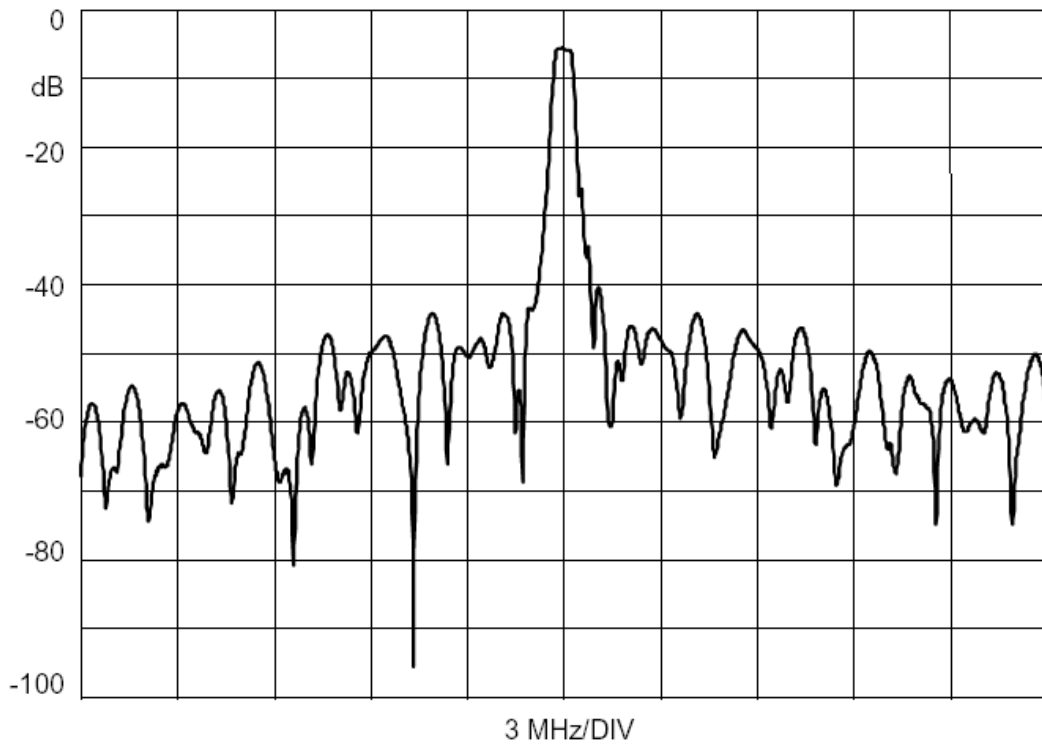
Impedance Matching to 50Ω Unbalanced	External L-C
Impedance Matching to 200Ω Balanced	External L-C
Impedance Matching to 50Ω Input / 400Ω Output	External L-C
Case Style	SMP9171-10 9.1 x 7.1 mm Nominal Footprint
Lid Symbolization (YY = year, WW = week, S= shift)	RFM, SF1115A, <u>YYWWS</u>



CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

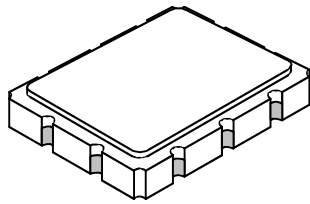
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.



SM9171-10 Case

10-Terminal Ceramic Surface-Mount Case

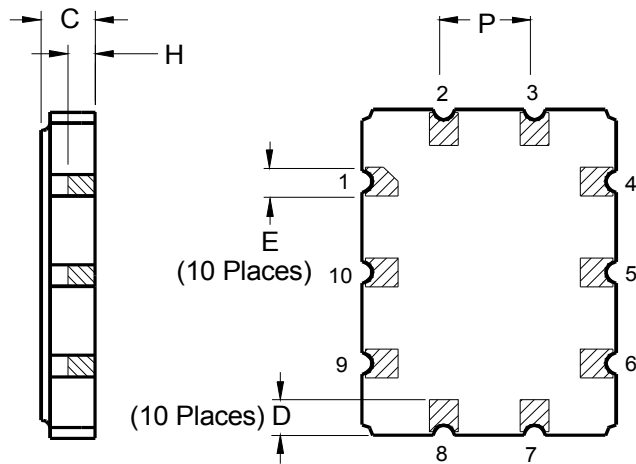
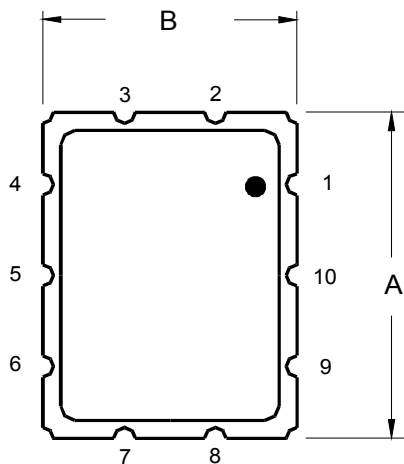
9.1 x 7.1 mm Nominal Footprint



Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	8.86	9.09	9.40	0.349	0.358	0.370
B	6.88	7.11	7.40	0.271	0.280	0.291
C		1.91	2.00		0.075	0.079
D		0.99			0.039	
E		0.79			0.031	
H		1.0			0.039	
P		2.54			0.100	

Materials	
Solder Pad Termination	Au plating 30 - 60 pinches (76.2-152 μm) over 80-200 pinches (203-508 μm) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 pinches Thick
Body	Al_2O_3 Ceramic
Pb Free	

Electrical Connections		
Connection		Terminals
Port 1	Input or Return	6
	Return or Input	5
Port 2	Output or Return	1
	Return or Output	10
Ground		All others
Single Ended Operation		Return is ground
Differential Operation		Return is hot



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

